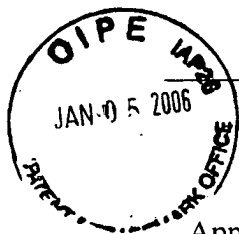


DPW

Please Direct All Correspondence to Customer Number **20995****AMENDMENT / RESPONSE TRANSMITTAL**

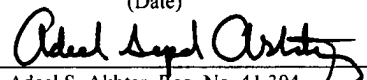
Applicant : Albertson, et al.
App. No : 10/713,845
Filed : November 14, 2003
For : MULTI-LAYER INTERCONNECT
WITH ISOLATION LAYER
Examiner : George A. Goudreau
Art Unit : 1763

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

January 3, 2006

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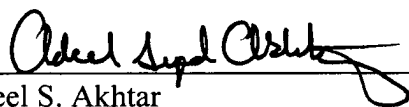

Adeel S. Akhtar, Reg. No. 41,394

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Transmitted herewith for filing in the above-identified application are the following enclosures:

- (X) Response to Restriction Requirement in 2 pages.
- (X) Return prepaid postcard.
- (X) Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.


Adeel S. Akhtar
Registration No. 41,394
Attorney of Record
Customer No. 20,995
(415) 954-4114



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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

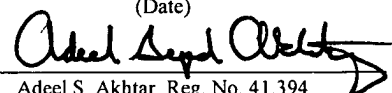
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January 3, 2006

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Adeel S. Akhtar, Reg. No. 41,394

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated December 9, 2005, Applicant submits the following remarks for consideration in connection with the above-identified patent application.